

OSRAM LT E63C

Datasheet

Not for new design

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Power TOPLED® Lens

LT E63C

PowerTOPLED with lens, a powerful member of the TOPLED family. Thanks to their high luminous efficacy, the LEDs are ideal for rear light clusters and indicators on vehicles and for display panels for traffic control systems.



Applications

- Electronic Equipment

Features

- Package: white PLCC-4 package, colorless clear resin
- Chip technology: InGaN
- Typ. Radiation: 20°
- Color: $\lambda_{\text{dom}} = 525 \text{ nm}$ (● true green)
- Corrosion Robustness Class: 3B
- Qualifications: AEC-Q102 Qualified
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

Ordering Information

Type	Partial Flux ¹⁾ $I_F = 30 \text{ mA}$ E_v	Ordering Code
LT E63C-BADB-35-1	1800 ... 7100 lx	Q65110A1981

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min.	-40 °C
		max.	100 °C
Storage Temperature	T_{stg}	min.	-40 °C
		max.	100 °C
Junction Temperature	T_j	max.	125 °C
Forward current $T_s = 25\text{ °C}$	I_F	max.	30 mA
Surge Current $t \leq 10\ \mu\text{s}; D = 0.005; T_s = 25\text{ °C}$	I_{FS}	max.	400 mA
Reverse voltage ²⁾ $T_s = 25\text{ °C}$	V_R	max.	5 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV

Characteristics

$I_F = 30 \text{ mA}$; $T_S = 25 \text{ °C}$

Parameter	Symbol		Values
Peak Wavelength	λ_{peak}	typ.	520 nm
Dominant Wavelength ³⁾ $I_F = 30 \text{ mA}$	λ_{dom}	min.	516 nm
		typ.	525 nm
		max.	534 nm
Spectral Bandwidth at 50% $I_{\text{rel,max}}$	$\Delta\lambda$	typ.	33 nm
Viewing angle at 50% I_V	2ϕ	typ.	20 °
Forward Voltage ⁴⁾ $I_F = 30 \text{ mA}$	V_F	min.	2.90 V
		typ.	3.50 V
		max.	4.40 V
Reverse current ²⁾ $V_R = 5 \text{ V}$	I_R	typ.	10 μA
		max.	0.01 μA
Temperature Coefficient of Peak Wavelength $-10\text{°C} \leq T \leq 100\text{°C}$	$TC_{\lambda_{\text{peak}}}$	typ.	0.04 nm / K
Real thermal resistance junction/solderpoint ⁵⁾	$R_{\text{thJS real}}$	max.	180 K / W

Brightness Groups

Group	Partial Flux ¹⁾ $I_F = 30 \text{ mA}$ min. E_v	Partial Flux ¹⁾ $I_F = 30 \text{ mA}$ max. E_v	Luminous Flux ⁶⁾ $I_F = 30 \text{ mA}$ typ. Φ_v
BA	1800 lx	2240 lx	500 mlm
BB	2240 lx	2800 lx	600 mlm
CA	2800 lx	3550 lx	800 mlm
CB	3550 lx	4500 lx	1000 mlm
DA	4500 lx	5600 lx	1300 mlm
DB	5600 lx	7100 lx	1600 mlm

For test method of partial flux measurement see Application Note: AN014 Partial flux — Measurement reliability of lensed LEDs

Forward Voltage Groups

Group	Forward Voltage ⁴⁾ $I_F = 30 \text{ mA}$ min. V_F	Forward Voltage ⁴⁾ $I_F = 30 \text{ mA}$ max. V_F
2	2.90 V	3.30 V
3	3.30 V	3.80 V
4	3.80 V	4.40 V

Wavelength Groups

Group	Dominant Wavelength ³⁾ $I_F = 30 \text{ mA}$ min. λ_{dom}	Dominant Wavelength ³⁾ $I_F = 30 \text{ mA}$ max. λ_{dom}
3	516 nm	522 nm
4	522 nm	528 nm
5	528 nm	534 nm

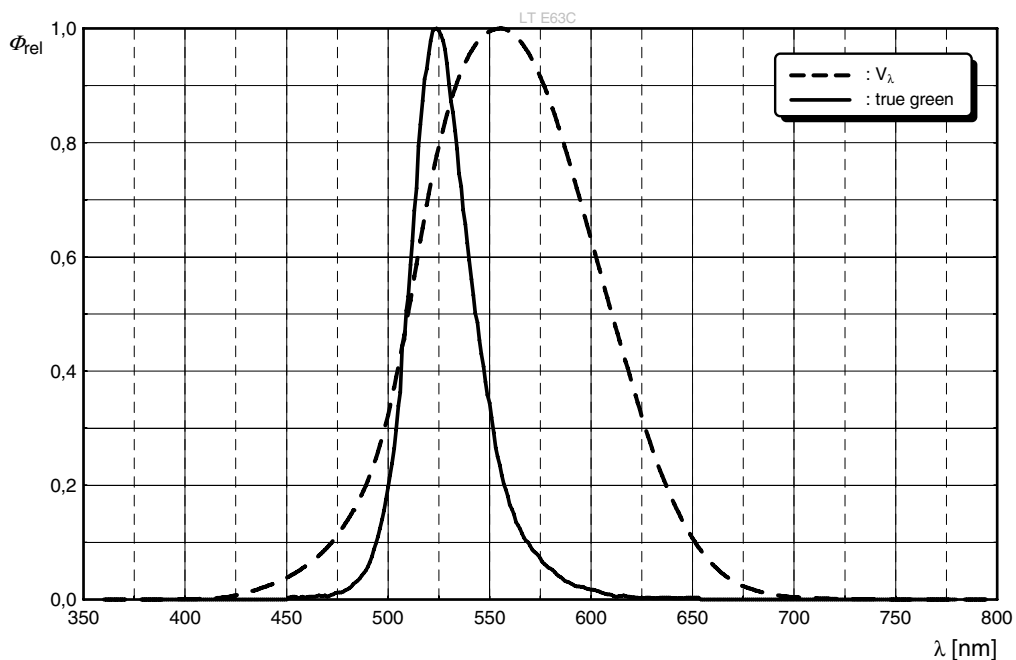
Group Name on Label

Example: BA-3-2

Brightness	Wavelength	Forward Voltage
BA	3	2

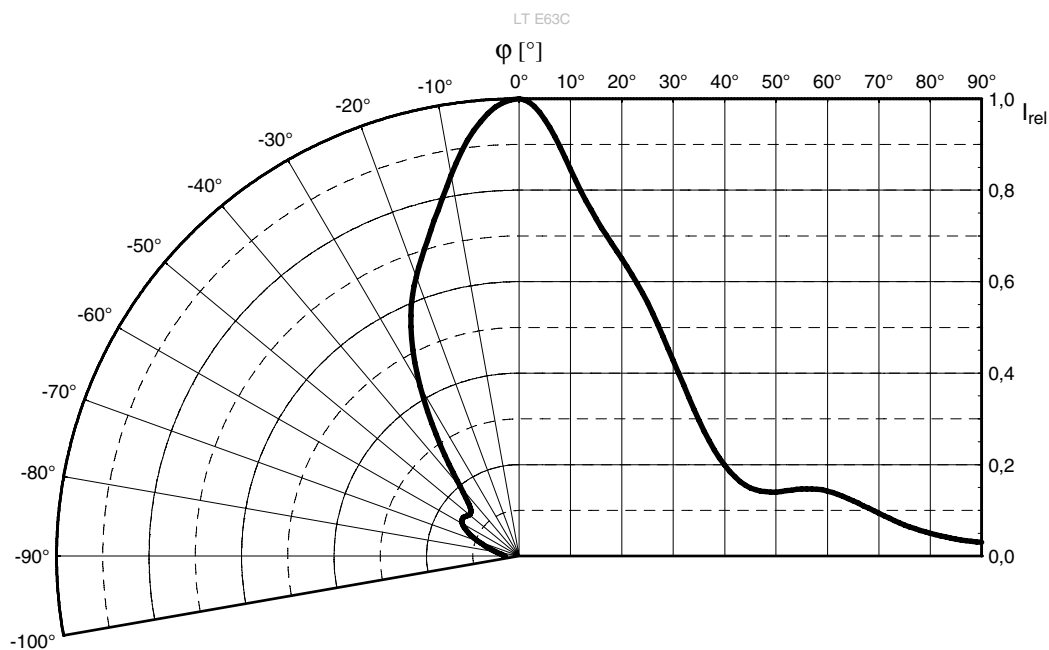
Relative Spectral Emission ⁶⁾

$I_{rel} = f(\lambda); I_F = 30 \text{ mA}; T_S = 25 \text{ }^\circ\text{C}$



Radiation Characteristics ⁶⁾

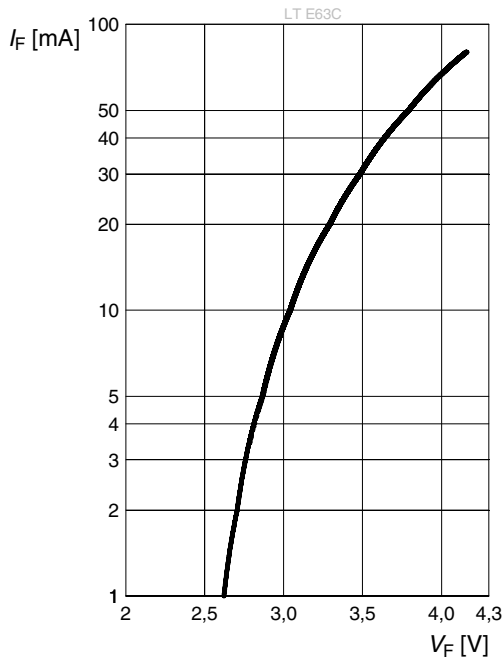
$I_{rel} = f(\phi); T_S = 25 \text{ }^\circ\text{C}$



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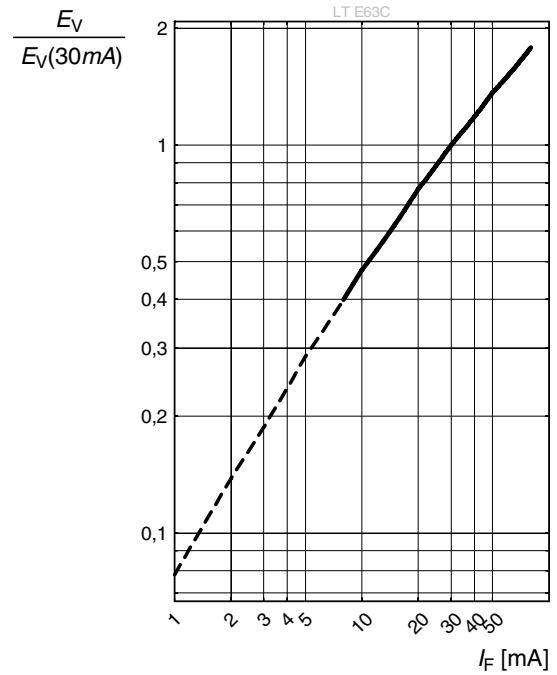
Forward current ^{6), 7)}

$$I_F = f(V_F); T_S = 25\text{ °C}$$



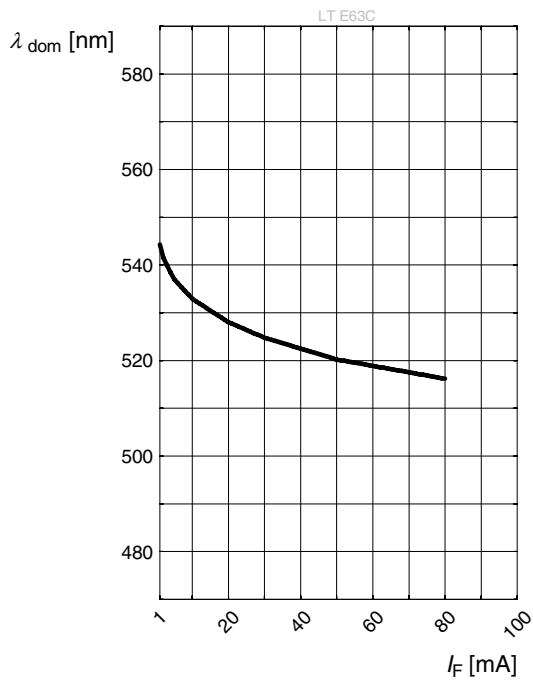
Relative Partial Flux ^{6), 7)}

$$E_V/E_V(30\text{ mA}) = f(I_F); T_S = 25\text{ °C}$$



Dominant Wavelength ⁶⁾

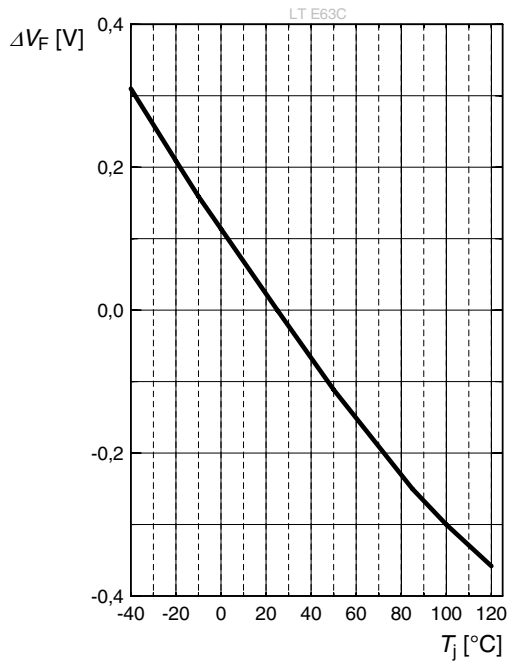
$$\lambda_{\text{dom}} = f(I_F); T_S = 25\text{ °C}$$



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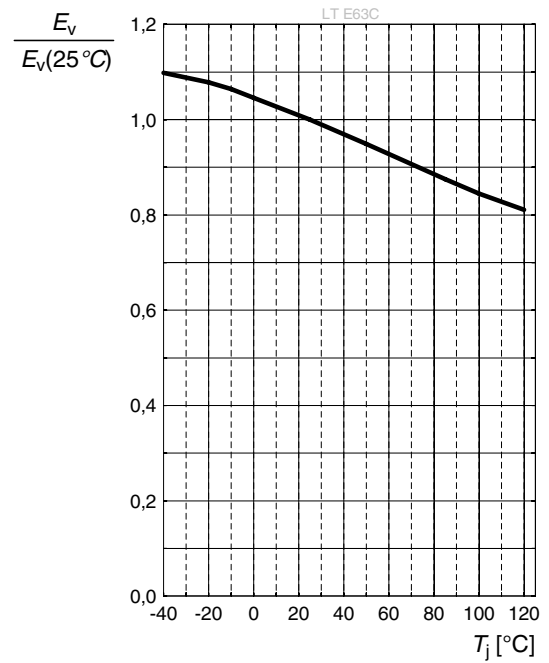
Forward Voltage ⁶⁾

$$\Delta V_F = V_F - V_F(25\text{ °C}) = f(T_j); I_F = 30\text{ mA}$$



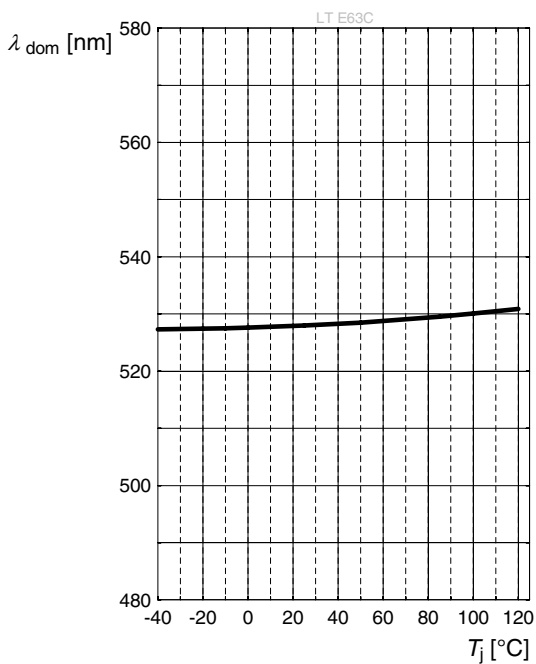
Relative Partial Flux ⁶⁾

$$E_v/E_v(25\text{ °C}) = f(T_j); I_F = 30\text{ mA}$$



Dominant Wavelength ⁶⁾

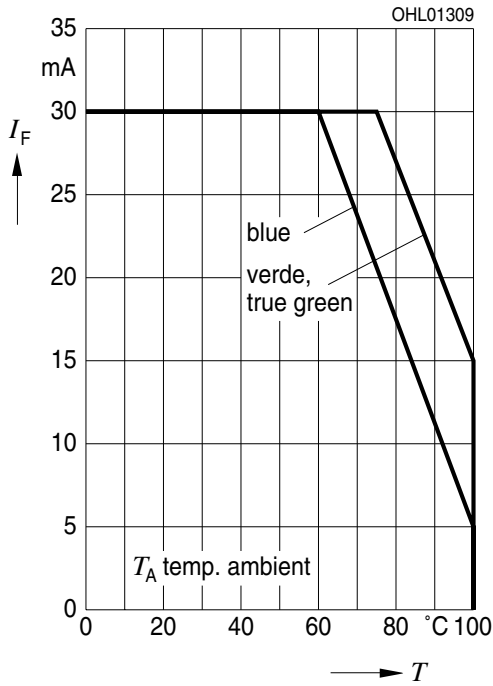
$$\lambda_{\text{dom}} = f(T_j); I_F = 30\text{ mA}$$



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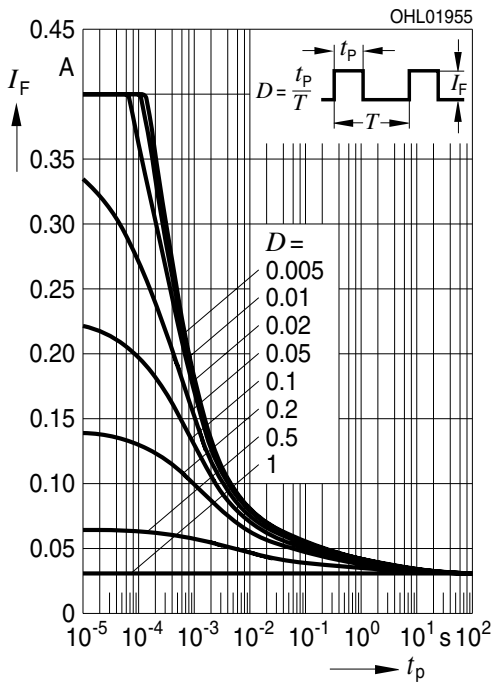
Max. Permissible Forward Current

$I_F = f(T)$



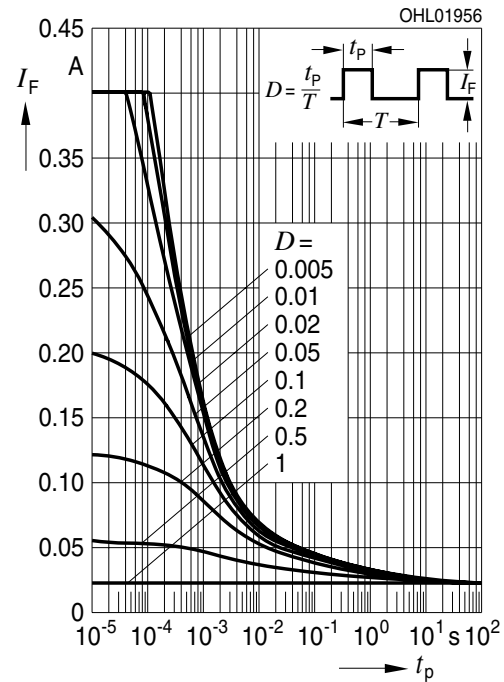
Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle; T_s = 25 °C



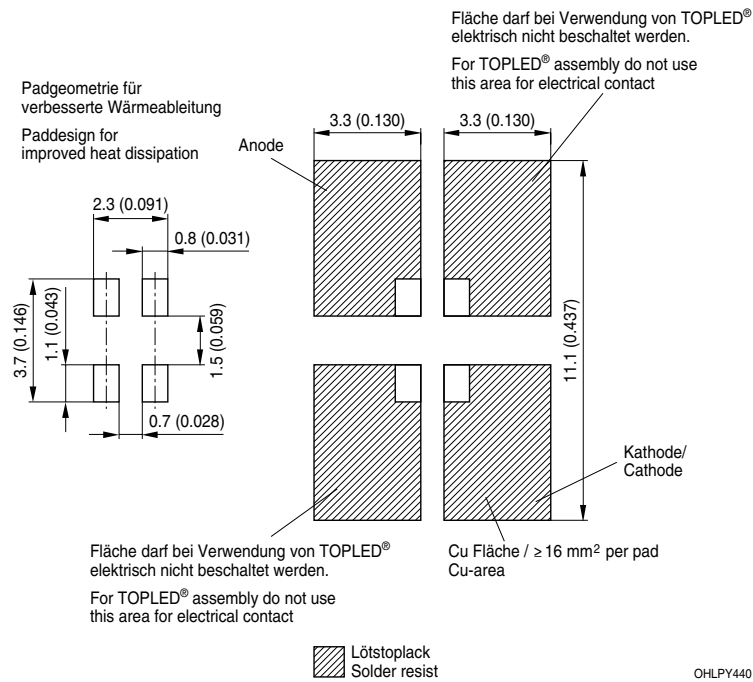
Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle; T_s = 85 °C



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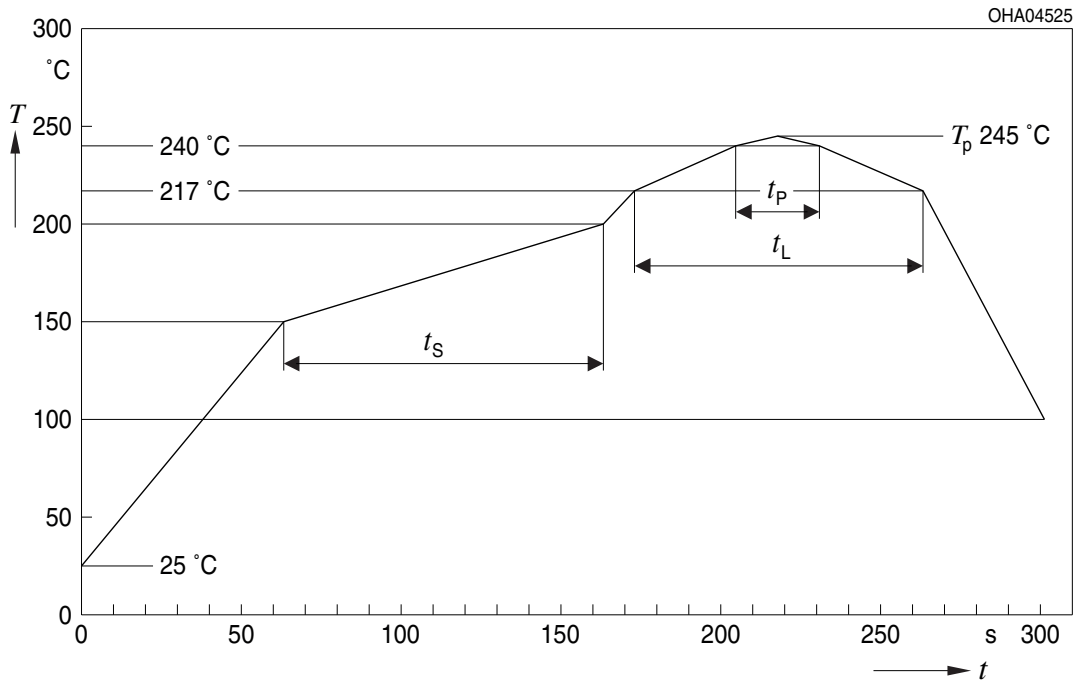
Recommended Solder Pad ⁸⁾



For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

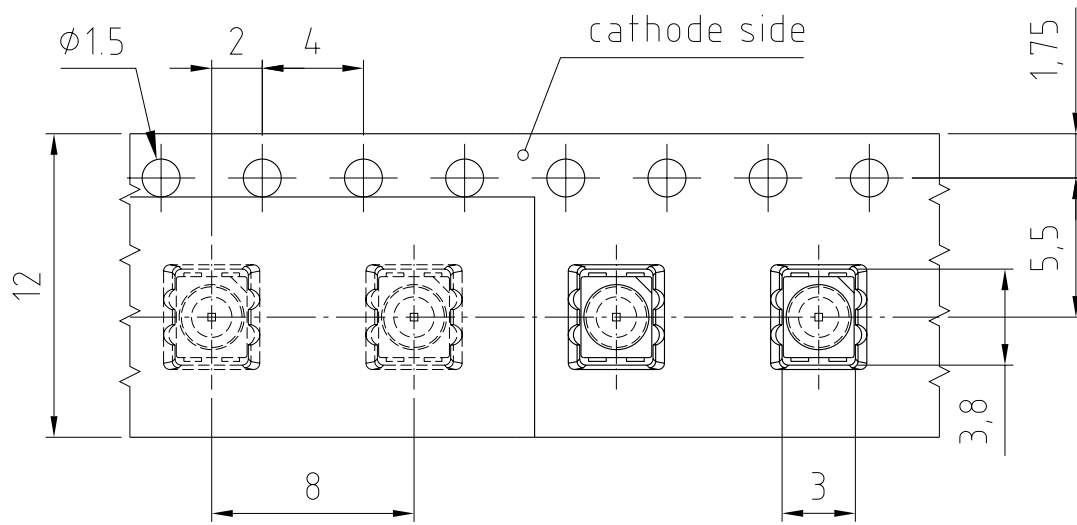


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak ^{*)} T_{Smax} to T_p			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_p		245	250	°C
Time within 5 °C of the specified peak temperature $T_p - 5 \text{ K}$	t_p	10	20	30	s
Ramp-down rate* T_p to 100 °C			3	4	K/s
Time 25 °C to T_p				480	s

All temperatures refer to the center of the package, measured on the top of the component
^{*)} slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

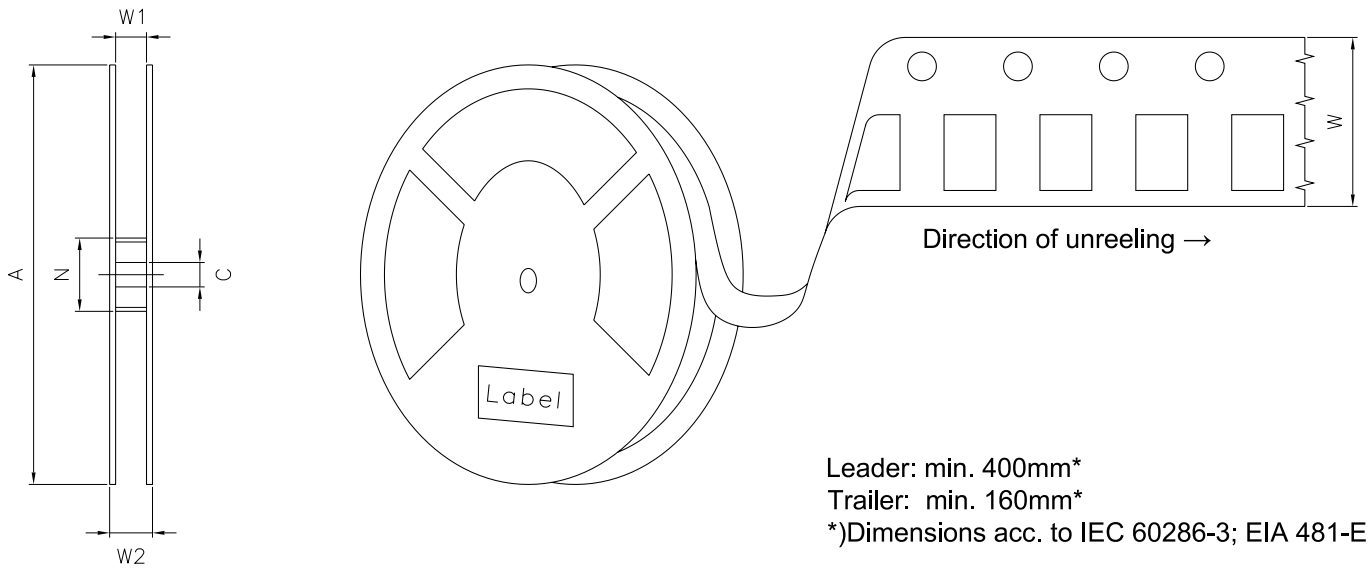
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Taping ⁸⁾



C63062-A3533-B01-02

Tape and Reel ⁹⁾



Reel Dimensions




A	W	N _{min}	W ₁	W _{2max}	Pieces per PU
330 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	2000

Barcode-Product-Label (BPL)


OSRAM Opto Semiconductors LX XXXX BIN1: XX-XX-X-XXX-X

RoHS Compliant

(6P) BATCH NO: 1234567890 ML Temp ST
X XXX °C X






(1T) LOT NO: 1234567890 (9D) D/C: 1234



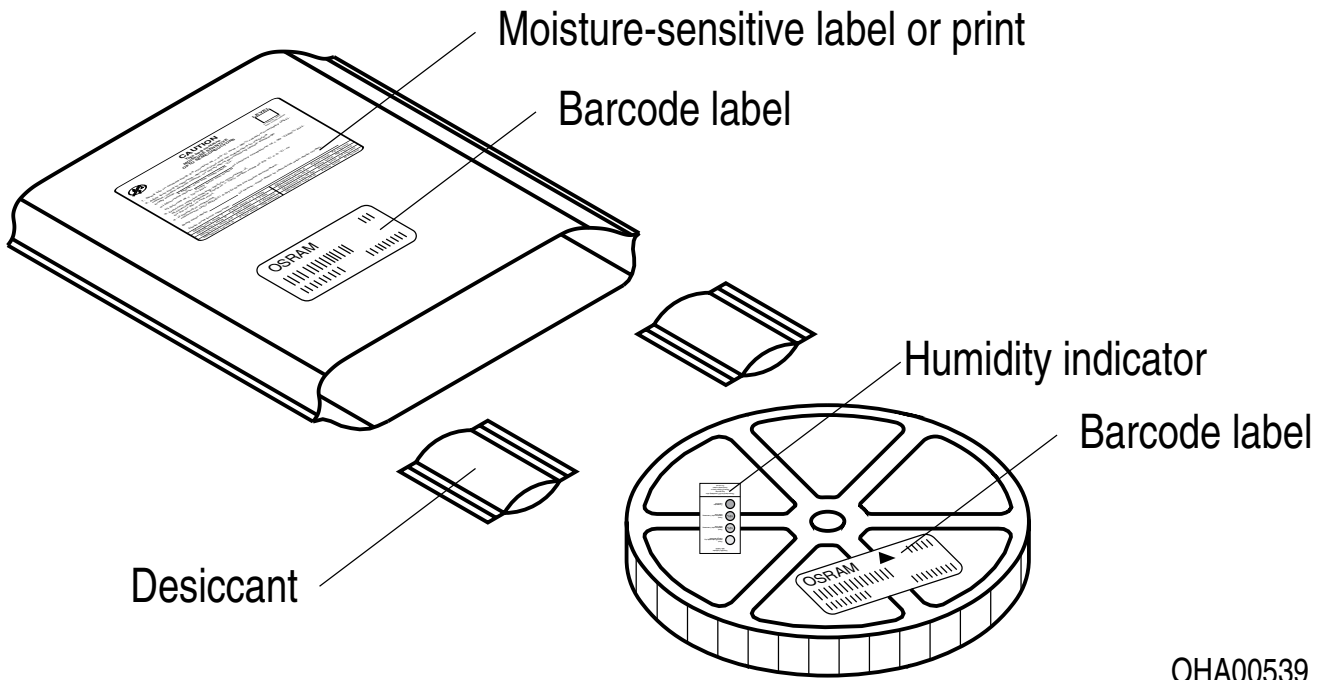
Pack: RXX
DEMY XXX
X_X123_1234.1234 X

(X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X



OHA04563

Dry Packing Process and Materials ⁸⁾

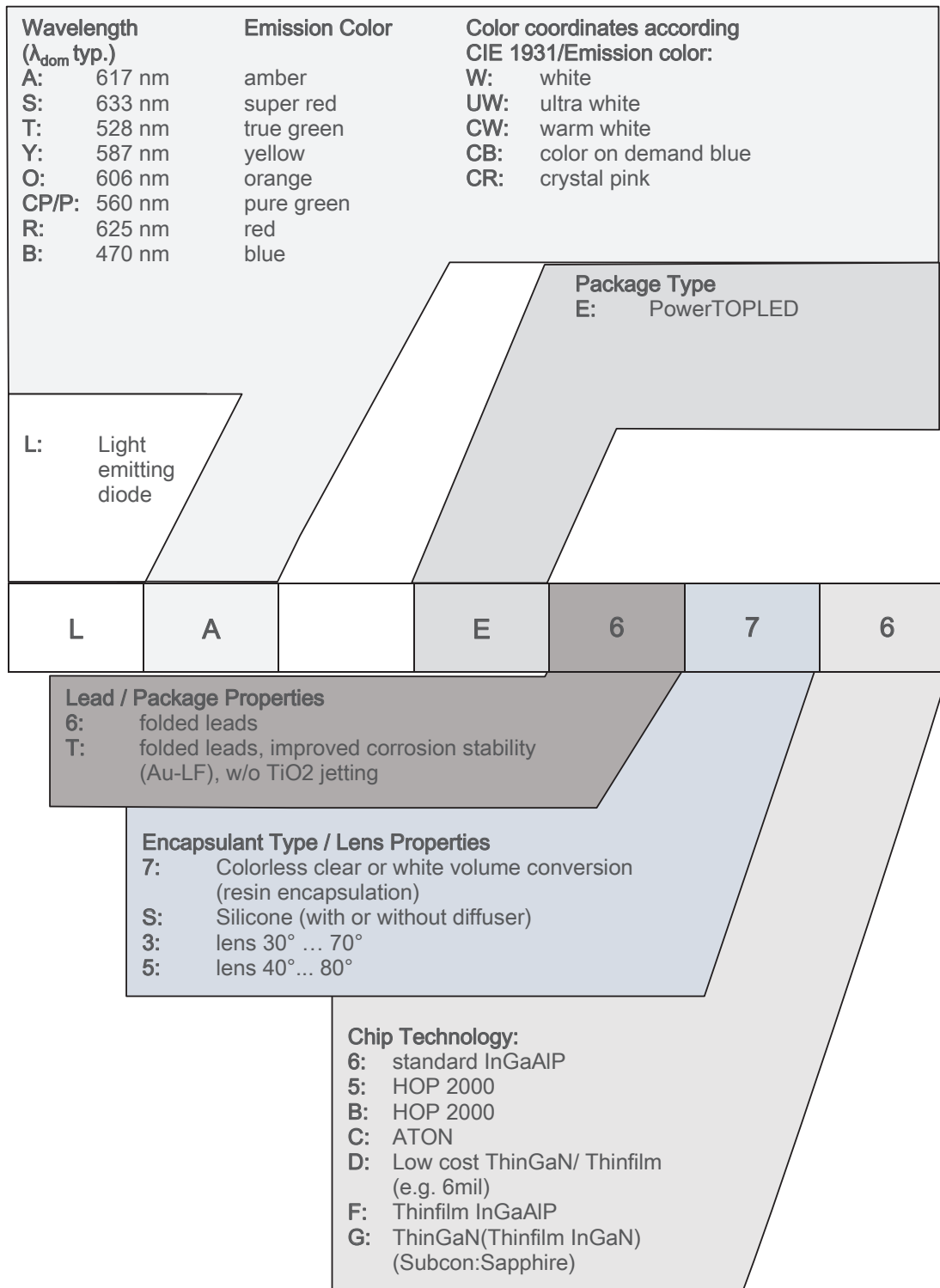


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Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

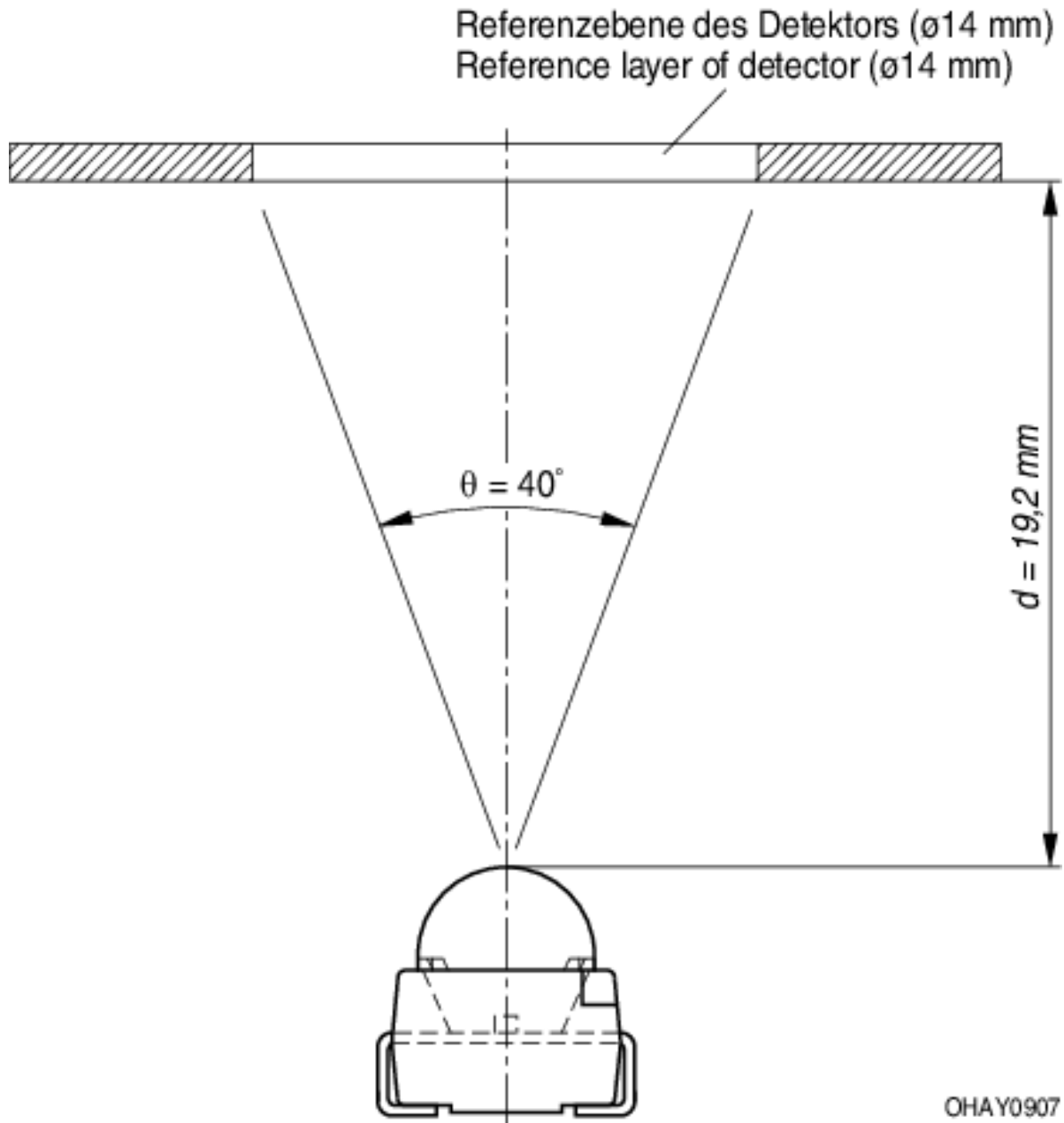
Not for new design

Type Designation System



Not for new design

Schematic test method for partial flux measurement



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.

Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of $\pm 8\%$ and an expanded uncertainty of $\pm 11\%$ (acc. to GUM with a coverage factor of $k = 3$).
- 2) **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- 3) **Wavelength:** The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ± 0.5 nm and an expanded uncertainty of ± 1 nm (acc. to GUM with a coverage factor of $k = 3$).
- 4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ± 0.05 V and an expanded uncertainty of ± 0.1 V (acc. to GUM with a coverage factor of $k = 3$).
- 5) **Thermal Resistance:** $R_{th\ max}$ is based on statistic values (6σ).
- 6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 9) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.5	2022-04-21	New Layout Not for new design

Not for new design

Not for new design



EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，
不含有毒有害物质或元素。

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